

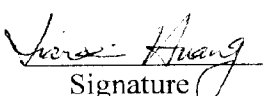
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04-09-1999



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Docket No. JCLA4388

Form 1595 1-31-92		RECORDATION FORM COVER SHEET PATENTS ONLY		U.S. Department of Commerce Patent and Trademark Office	
To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.					
1. Name of conveying party(ies): Chingfu Lin		2. Name/address of receiving Party(ies): Worldwide Semiconductor Manufacturing Corp. No. 25, Li-Hsin Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.			
3. Nature of conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Other <input type="checkbox"/> Change of Name <input type="checkbox"/> Reassignment		Add'l names of receiving parties Attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No			
4. Date(s) of execution: Mar. 15, 1999.					
5. Application number(s) or patent number(s): If this documents is being filed together with a new application, the execution date of the application is Mar. 15, 1999.					
A. Patent Application No. (s) Additional numbers attached ? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		B. Patent No. (s)			
6. Name and address of party to whom correspondence concerning document should be mailed: J.C. Patents, Inc. 1340 Reynolds Ave., Suite 114 Irvine, CA 92614 (949) 660-0761		7. Total No. of applications and patents involved: ONE(1)			
		8. Total fee (37 CFR §3.41): \$40.00 <input checked="" type="checkbox"/> Enclosed <input type="checkbox"/> Charge to Acct. No.			
		9. Total number of pages, including cover sheet, attachments and document 3.			
DO NOT USE THIS SPACE					
10. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Jiawei Huang Name of Person Signing  Signature 3/29/99 Date					

Registration No. 43, 330

04/08/1999 DNGUYEN 00000279 09282052

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JCS25 U.S. PTO
09/282052



ASSIGNMENT

WHEREAS,

1. Chingfu Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD FOR PLANARIZING POLYSILICON LAYER**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Worldwide Semiconductor Manufacturing Corp.
of No. 25, Li-Hsin Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

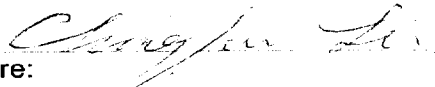
hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

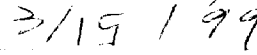
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.


Signature:


Date:

Sole or First Joint Inventor: Chingfu Lin